

					M-7744 US	09 436,158		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT					Applicant			
(Use several sheets if necessary)					Perez et al.			
					Filing Date	Group		
					11 09 99	2811		
U.S. Patent Documents								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
	AA							
	AB							
	AC							
	AD							
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
RLT	AL	6-54749 w Eng. Abs.	3/2/89	Japan	H01L	23/28		X
	AM	60-52050 w Eng. Abs.	3 23 85	Japan	H01L	23 48		X
	AN	97-72358	11/7/97	Korea	H01L	23/50		X
MT	AO	94-1979	1 8 94	Korea	H01L	21 56		X
	AP							
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
MT	AQ	Glenn et al., USSN 09 176,614, Filed 10 21 98 entitled "Plastic Integrated Circuit Device Package and Micro-Leadframe and Method for Making the Package"						
MT	AR	Glenn, Thomas P., USSN 09 324,710, Filed 06 03 99 entitled "Plastic Package for an Optical Integrated Circuit Device and Method of Making"						
	AS							

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U.S. Patent Documents								
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate		
lit	AA 5,521,429	5 28 96	Aono, et al.	257	676			
	AB 5,981,314	11 9 99	Glenn, et al.	438	127			
	AC 6,143,981	11 7 00	Glenn	174	52.4			
	AD 5,336,931	8/9/94	Juskey, et al.	257	787			
	AE 5,977,613	11 2 99	Takata, et al.	257	666			
	AF 5,200,362	4/6/93	Lin, et al.	437	207			
	AG 5,776,798	7/7/98	Quan, et al.	438	112			
	AH 3,838,984	10/1/74	Crane, et al.	29	193.5			
	AI 4,530,152	7/23/85	Roche, et al.	29	588			
	AJ 5,041,902	8/20/91	McShane	357	79			
lit	AK 5,157,480	10/20/92	McShane, et al.	357	74			
Foreign Patent Documents								
							Translation	
	Document	Date	Country	Class	Subclass	Yes	No	
lit	AL 57-45959 w/Eng. Abs.	3/16/82	Japan	H01L	23/28			
	AM 62-9639 w/Eng. Abs.	1/17/87	Japan	H01L	21/56	X		
	AN 61-39555 W/Eng. Abs.	2/25/86	Japan	H01L	23/36			
	AO 63-205935 w Eng. Abs.	8 25 88	Japan	H01L	23 28			
	AP 63-233555 w Eng. Abs.	9 29 88	Japan	H01L	23 30			
lit	AQ 7-312405	11 28 95	Japan	H01L	23 50	X		
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
	AR							
	AS							

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U.S. Patent Documents								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
NT	AA	5,172,213	12/15/92	Zimmerman	257	796		
	AB	5,172,214	12/15/92	Casto	257	676		
	AC	5,258,094	11/2/93	Furui, et al.	156	634		
	AD	5,278,446	1/11/94	Nagaraj, et al.	257	707		
	AE	5,435,057	7/25/95	Bindra, et al.	29	830		
	AF	5,701,034	12/23/97	Marrs	256	706		
	AG	5,783,861	7/21/98	Son	253	693		
	AH	5,835,988	11/10/98	Ishii	257	684		
	AI	5,859,471	11/12/99	Kuraishi, et al.	256	666		
	AJ	5,866,939	2/2/99	Shin, et al.	257	666		
	AK	5,877,043	3/2/99	Alcoe, et al.	438	123		
NT	AL	5,894,108	4/13/99	Mostafazadeh, et al.	174	52.4		
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
NT	AM	8-125066	5/17/96	Japan	H01L	23/12	X	
	AN	8-306853	11/22/96	Japan	H01L	23/50	X	
	AO	9-8205	1/10/97	Japan	H01L	23/50	X	
	AP	9-8206	1/10/97	Japan	H01L	23/50	X	
	AQ	9-8207	1/10/97	Japan	H01L	23/50	X	
NT	AR	9-92775	4/4/97	Japan	H01L	23/50	X	
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
	AS							
	AT							

U.S. Department of Commerce, Patent and Trademark Office

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*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
Not	AA 5,977,630	11/2/99	Woodworth, et al.	257	712	
	AB 4,707,724	11/17/87	Suzuki, et al.	357	71	
	AC 4,756,080	7/12/88	Throp, Jr., et al.	29	827	
	AD 5,273,938	12/28/93	Lin, et al.	437	207	
Not	AE 5,604,376	2/18/97	Hamburgen, et al.	257	676	
	AF					
	AG					

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							Translation	
	Document	Date	Country	Class	Subclass		Yes	No
Not	AH 55-163868 w/Eng. Abs.	12/20/80	Japan	H01L	23/48			
	AI 60-195957 w/Eng. Abs.	10/4/85	Japan	H01L	23/48			
	AJ DE 19734794 A1	8/11/97	German	H01L	23/50			X
	AK JP6092076 W/Eng. Abs.	4/5/95	Japan	B42D	15/10			X
	AL 59-227143	12/20/84	Japan	H01L	23/12			X
Not	AM EP 0794572 A2	9/10/97	EPO	H01L	23/495			

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AN	
AO	
AP	

Examiner *Not* Date Considered *4/12/01*

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Includes cases of the prior art.